ELECTROLYTIC CAPACITORS

ALUMINUM ELECTROLYTIC CAPACITORS
SOLID CONDUCTIVE POLYMER CAPACITORS
HYBRID CONDUCTIVE POLYMER CAPACITORS

GENERAL PRECAUTIONS AND GUIDELINES
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1. GENERAL PRECAUTIONS & GUIDELINES

In the following Precautions and Guidelines, CapXon provides instructions and requirements to assure a proper handling and desired performance of capacitors. Firstly, all general information is given, which applies to all technologies. The following chapters provide additional instructions specifically about technology and mounting style, which completes the full set of instructions.

1.1. GENERAL - ALL TYPES -

1.1.1. POLARITY

All conventional Electrolytic Capacitors have a polarity due to the internal construction. This polarity is marked on the component by printing on the top of component or on the sleeve of Aluminum Electrolytic Capacitors, including Radial, Snap-In and Screw types.

Any reverse voltage can cause short circuit breakdown of capacitor or leakage of electrolyte. Electrolytic Capacitors isn’t designed for AC-voltage supply and only meant for DC-voltage applications.

For an application where polarity in circuit can be reversed or unknown, specific bi-polar aluminium electrolytic capacitors shall be used. We offer such components within our product range.

1.1.2. OVERVOLTAGE

Overvoltage can damage the capacitor and can cause a drastic increase in leakage current, which possibly shortens the lifetime of the capacitor. In a worst case, short circuit failure mode can happen. As a result, do not apply any continuous or temporary overvoltage.

The applied operating voltage, which is applied to the capacitor, should not exceed the rated voltage of the capacitor.

1.1.3. OPERATING TEMPERATURE

Only operate the capacitor within the limits of allowed temperature range, which is specified by datasheet. Be aware that the sum of thermal stress by ambient condition plus electrical stress is the main driving factor for aging. As the thermal stress level gets higher, the expected capacitor lifetime would be lower.

A drop in applied temperature, ambient condition or cooling within application can enlarge the expected lifetime of the capacitor. For details, please see further documentation of lifetime estimation.

1.1.4. RIPPLE CURRENT

The applied ripple current shall not exceed the stated max. ripple current I_r on the datasheet at the specific frequency.

When capacitors are overstressed by ripple, it can generate massive heat inside the capacitor, which can result in deterioration, vent operation or capacitor breakage.

1.1.5. CHARGE AND DISCHARGING

Frequent and quick charge / discharge generates heat inside the capacitor and can cause possible increase of leakage current, reduction of the expected lifetime, decrease of capacitance, vent operation or breakage.

For such applications please see design rules or consult our technical support for assistance.

1.1.6. SOLDERING CONDITIONS

For recommended reflow solder profile, please see additional information at Section 2. Soldering Instructions.

Soldering by vapor phase for SMD types or any hand soldering are not recommended. No permission is released by CapXon side either. In case of such a usage, customer need to validate solder result and applied component stress within their own manufacturing process.

1.1.7. MSL – MOISTURE SENSITIVE LEVEL (ONLY FOR SMD TYPES)

Our standard SMD components are rated according to JEDEC J-STD020 with MSL1. Construction of this part does not include hygroscopic critical materials and are not prone to delamination or popcorn effects. Only SMD MLPC types of the Solid Conductive Polymer components have MSL3. Moreover, only this type requires additional actions or specific handling in factory floor by customer such as handling or storing the goods after opening the package in accordance to JEDEC J-STD020.

1.1.8. RESISTANCE TO CHEMICALS AND SOLVENTS FOR WASHING, GLUING, FILLING AND COATING

Due to the wide variety of suppliers and different chemical formulas of washing, gluing, filling and coating materials, the individually used material and appliance process need to be validated by customer itself. It is not possible to provide any global material usage approval from our side.
CapXon can provide additional information, including combination of chemicals which could be critical to the component behavior and can support measurements of component performance after application of washing, gluing, filling or coating materials. For specific support, please kindly contact our technical support for further advices.

1.1.9. CLEANING AND WASHING

Do not wash the assembled capacitors with the following cleaning agents:

- **Xylene**
  - can cause deterioration of the rubber seal material
- **Halogenated solvents**
  - can cause corrosion and electrical failure modes
- **Petroleum based solvents**
  - can cause degeneration of the rubber seal material
- **Alkali based solvents**
  - can cause corrosion and dissolving of aluminum can
- **Acetone**
  - component marking possibly dissolve

After finishing cleaning and washing, the below points need to be verified by customer:

Dry all solvents properly from PCB as well as capacitor surface sufficiently and apply air blower or air knife, with temperatures within the temperature range of the product specification, if needed.

Monitor pH value, conductivity, specific gravity and water content of cleaning solvents to be sure of possible contaminations and pollution. Contaminations can negatively affect the performance of the capacitor.

1.1.10. GLUING, FILLING OR COATING

It is not allowed to use any gluing (adhesives), filling or coating materials, which contains halogenated solvents. Halogen ions are critical, because they can diffuse or creep in the capacitor through rubber sealing and can possibly damage the internal capacitor element /structure result in serious failure modes for the capacitor.

Additionally, please pay attention to the following points:

- Make sure that the surface of capacitor and the area between component bottom / rubber sealant is dry and clean before appliance of gluing, filling or coating material. It is important to avoid any contamination with chemical residues (e.g. flux residues, cleaning).
- Please follow and meet the stated gluing, coating, filling, heating and curing instructions from manufacturer or supplier of such materials. Be aware of possible shrinkage of such materials. Verify that the hardening was properly done and that no solvents / agents do remain.
- There should be no excessive heat nor mechanical pressure /stress at any stages from the production on customer side. Be aware of the possible material shrinkage of used material. High material shrinkage which leads to damage on capacitor is not CapXon’s responsibility.
- The used materials of gluing, coating or filling can possibly react with the marking of component and this can change optical appearance such as the appearance and legibility.
- If the rubber seal surface is fully covered by gluing, filling or coating material, it is no longer possible to have a natural diffusion of gas between the inside of the capacitor and the ambient. So, to avoid such situation, it’s strongly recommended to block maximum 80% of the sealed section on the bottom side of the capacitor.

Please find the example below of how gluing could be applied on Radial and Snap-In types.

![Gluing reference example of a Snap-In capacitor](image)

1.1.11. OPERATION AND ENVIRONMENT

As long as the application is powered, in operation and cap is not discharged, the user is never permitted to touch the electric terminals of the capacitor directly or to bridge the terminals by hand or any other conductive liquid or solid material. Otherwise, a short circuit of terminals can happen and a hard discharge can damage capacitor / application as well as it can harm the operator.

Within operation, please avoid the following environmental conditions to assure proper capacitor operation:

- high vibration, shocks or mechanical stress. For tested and allowed conditions, please see available references or contact us for details
- avoid direct sunlight, ozone and any kind of radiation or ultraviolet rays
- corrosive or toxic gases (e.g. ammonium, chlorine

For further information please contact sales@capxon.org
and compounds, bromine and compounds, hydrogen sulfide, sulfuric acid)
- ambient with high amount of damp condensation, water or types of oil

1.1.12. MECHANICAL STRESS

Best possible, avoid mechanical stress for the capacitor and do not apply any excessive mechanical stress to the lead wire pins or terminal.

After mounting, do not lift nor carry the PCB assembly by just grabbing the capacitor to pick up the board.

1.1.13. STORAGE

In case of long-term storage without applying voltage to the capacitor, leakage current tends to increase.

By applying the rated voltage before usage, the dielectric layer of aluminium oxide and leakage current can be stabilized.

If the capacitor is for more than 12 months, it is recommended to apply the DC rated voltage $V_R$ for 30 minutes through 1k$\Omega$ protective series resistor.

The storage conditions for storage on customer side should be monitored and controlled to a temperature of 5°C up to 35°C and less than 75% rel. humidity.

1.1.14. DISPOSAL

Please follow your local governmental and organizational restrictions for disposal and if needed, contact your local responsible for correct handling.

In case of incineration, punch holes in the aluminum can in advanced to avoid explosion of capacitor and then burn with at least 800°C, otherwise it can result toxic gas.

1.2. ALUMINUM ELECTROLYTIC & HYBRID CONDUCTIVE POLYMER CAPACITORS - ALL MOUNTING STYLES -

1.2.1. VENT & VENT OPERATION AT EMERGENCY

As a safety feature, most our regular electrolytic capacitors have a so-called vent, which is a pre-determined breaking point. In case of overstressed component, it can lead to internal gassing and due to this an internal overpressure will result in vent operation. So, the vent will open to release such pressure and gas can become visible. If user detects vent operation or gassing out of the capacitor when operating, disconnect the application immediately from power supply to turn it off directly. If it can’t be turned off, the capacitor or the conductive liquid / gas of electrolyte can result in short-circuits, which can dramatically damage the application.

Please notice to avoid being near with body or face above or in direction of capacitors vent when powered. When the running application is overstressed, gas leakage by vent is possible. By this gas with temperatures higher than 100°C can occur and can hurt human body and face. In such an event, if contact with skin, wash it immediately with plenty of water and soap. If contact with eyes, rinse immediately (e.g. eye shower) with plenty of water. If gas is inhaled, gargle right away with plenty of water. For all three cases, please consult a doctor for medical advices.

For proper operation of vent, consider space between the vent and covering surfaces (e.g. housing) as stated at the table below, it is strongly recommended for your mechanical construction / build-up of your product:

<table>
<thead>
<tr>
<th>Case diameter $\phi$</th>
<th>Clearance distance CI</th>
</tr>
</thead>
<tbody>
<tr>
<td>6.3mm to 16mm</td>
<td>Min. 2mm</td>
</tr>
<tr>
<td>18mm to 35mm</td>
<td>Min. 3mm</td>
</tr>
<tr>
<td>≥ 40mm</td>
<td>Min. 5mm</td>
</tr>
</tbody>
</table>

Minimum distance to be observed for the safe operation of the capacitor

Recommended minimum clearance distance between topside capacitor and device case

If such a space is not provided, the vent will not operate completely or even cannot open in case of overpressure.
1.2.2. SLEEVE MATERIAL (NOT FOR SMD)

The standard sleeve material for the majority of our Radial, Snap-In and Screw mounting capacitors is PET and for some series PVC is used as sleeve material. When sleeve is exposed to xylene, toluene or similar and afterwards exposed to high heat, the sleeve may be cracked or damaged.

The sleeve is not used as insulating material or layer and does not insulate capacitor to surroundings. For needed insulation, further actions need to be considered by customer and please follow our recommended design rules.

Sleeves are applied for all Aluminum Electrolytic Capacitors with Radial, Snap-In or Screw mounting and if desired for further customized solutions.

1.3. ALUMINUM ELECTROLYTIC
   - RADIAL TYPE -

1.3.1. PIN CUTTING & BENDING

Please take absolute care when cutting or bending pins, that the pin is fixed mechanically in direction of rubber sealant. It is necessary that the mechanical force while cutting and bending, which results in pulling or pressing force on pin, does not stress the inner construction of capacitor element or to damage the rubber sealant. Excessive pulling or pressing force on the pin with missing fixation can result in damage of internal pin to capacitor element connection and also the sealing can be weakened. So, please take care to assure appropriate cutting and bending. Do not pre-damage the capacitors and shorten their lifetime performance by incorrect handling.

1.3.2. SOLDERING

For recommended wave solder profile, please see additional solder instruction at section 2.5.

Improper soldering conditions may shrink or break the sleeve. Additionally, excessive heat can damage the internal capacitor element as terminals and lead wires conduct heat into the capacitor.

1.4. ALUMINUM ELECTROLYTIC CAPACITORS
   - SCREW TYPE -

1.4.1. MAINTENANCE

A regular inspection is recommended when screw capacitors are used at industrial applications. Before inspection, make sure to turn off the power, discharge screw capacitors carefully and do not apply mechanical force or pressure to the terminal to avoid damage. Inspection items are as stated below:

- Check on outer damage, deformation and electrolyte leakage
- Check electrical performance: leakage current, capacity, DF value and other product specifications. If there is any abnormality detected, make sure a capacitor replacement will be done and handled properly

1.4.2. MOUNTING & INSTALLATION

Make sure capacitors rated capacitance, rated voltage and polarity is according to spec before installation. Please confirm that capacitors and circuit board terminal pitch is consistent to each other before installation. It may cause stress to internal capacitor element through the terminal. if the pitch is different, mounting was done nevertheless and strong mechanical force was applied. In such case, this can cause short-circuit and other failure modes. Machine automated force pressure and lead bending strength must be controlled properly when mounting happens with automated machine.

1.4.3. MOUNTING POSITION OF SCREW TYPE CAPACITORS

To avoid screw capacitor breakage / explosion, it is not allowed to be mounted with the safety vent downwards to ground, because vent can’t function properly when mounted with vent to bottom side and existing gas pressure cannot release properly. Recommended mounting method is shown as figure below, to avoid any safety vent downwards installation. So, capacitor should be mounted with screw terminals up as shown below:

For further information please contact sales@capxon.org
**1.4.4. HORIZONTAL MOUNTING**

For horizontal mounting following mounting is strongly recommended. Anode terminal in upper position with safety vent in horizontal position as figure below on left side or safety vent in upper position with anode and cathode terminal in horizontal as figure below on right side.

**Recommended mounting position**

![Recommended mounting position](image1)

**Recommended mounting position, also in accordance to EIAJ RCR-2367C**

It may not damage capacitors directly, but an electrolyte leakage may happen, if installed by other mounting method in horizontal direction.

**1.5. SOLID CONDUCTIVE POLYMER CAPACITORS**

**1.5.1. APPLICATION RESTRICTIONS**

The leakage current of Solid Conductive Polymer Capacitors may vary which depends on thermal stress.

Please don’t use Solid Conductive Polymer Capacitors in the following types of applications / circuits:

- High-impedance circuits - which are meant to sustain voltages
- Coupling circuits

- Time constant circuits - in addition to the leakage current fluctuation, capacitance may also fluctuate, which depends on operational temperature and humidity. The fluctuation of the capacitance may cause problems, if it is used as a time constant capacitor, which is extremely sensitive to the fluctuation of the capacitance. So, do not use it as a time constant capacitor.

- Other circuits - which are significantly affected by leakage current. If you want to use 2 or more capacitors in a series connection, please contact us before usage.

**1.5.2. SUDDEN CHARGE AND DISCHARGE**

Do not use the capacitor in circuits when capacitor is repetitively charged and discharged rapidly. If repetitively and rapid charging and discharging stresses the capacitor, it can result in reduction of capacitance or may cause further damage due to internal heating. The usage of a protective circuit is recommended to ensure reliability, when rush currents exceeds 10 times of capacitors allowed max. ripple current $I_{R}$, but never more than max. 10A. When measuring the leakage current, a protective resistor ($1 \, k\Omega$) must be inserted to the circuit during the charge and discharge.
2. SOLDERING INSTRUCTIONS

In the following sections CapXon's leadfree solder profiles are stated in detail.

2.1. REFLOW SOLDERING • SMD – ALUMINUM ELECTROLYTIC CAPACITORS

Recommended reflow soldering conditions

Classification of reflow soldering profile

<table>
<thead>
<tr>
<th>Profile Features</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Preheat temperature min.</td>
<td>$T_{t_{\text{min}}}$ 150 °C</td>
</tr>
<tr>
<td>Preheat temperature max.</td>
<td>$T_{t_{\text{max}}}$ 180 °C</td>
</tr>
<tr>
<td>Preheat time $t_s$ from $T_{t_{\text{min}}}$ to $T_{t_{\text{max}}}$</td>
<td>$t_s$ 120 seconds</td>
</tr>
<tr>
<td>Ramp-up rate ($T_e$ to $T_p$)</td>
<td>max. 3 °C/second</td>
</tr>
<tr>
<td>Liquidous temperature</td>
<td>$T_L$ 217 °C</td>
</tr>
<tr>
<td>Time $t_L$ maintained above $T_L$</td>
<td>$t_L$ See reference table below for Ø Diameter / Rated Voltage $V_R$ combination</td>
</tr>
<tr>
<td>Peak package body temperature</td>
<td>$T_p$ See reference table below for Ø Diameter / Rated Voltage $V_R$ combination</td>
</tr>
<tr>
<td>Timeframe of within 5°C below and up to max actual peak body temperature</td>
<td>$t_p$ See reference table below for Ø Diameter / Rated Voltage $V_R$ combination</td>
</tr>
<tr>
<td>Ramp-down rate ($T_L$ to $T_p$)</td>
<td>max. 6 °C/second</td>
</tr>
<tr>
<td>Time 25°C to peak temperature</td>
<td>max. 8 minutes</td>
</tr>
</tbody>
</table>

* Limitations of ramp rates to JEDEC-J-STD020E

Package classification reflow temperature for SMD – Aluminum Electrolytic Capacitors

<table>
<thead>
<tr>
<th>Ø Diameter (mm)</th>
<th>$V_R$ * Rated Voltage (V)</th>
<th>$t_L$ * Time above 217°C</th>
<th>Time above 230°C</th>
<th>$T_P$ Peak Temperature</th>
<th>$t_p$ Timing (seconds)</th>
<th>Allowed Reflow Runs</th>
</tr>
</thead>
<tbody>
<tr>
<td>4 up to 6.3</td>
<td>4 to 50</td>
<td>90 sec. max.</td>
<td>30 sec. max.</td>
<td>260 °C</td>
<td>10</td>
<td>max. twice</td>
</tr>
<tr>
<td></td>
<td>63 to 100</td>
<td>60 sec. max.</td>
<td>30 sec. max.</td>
<td>255 °C</td>
<td>5</td>
<td>max. twice</td>
</tr>
<tr>
<td>8 up to 10</td>
<td>4 to 50</td>
<td>60 sec. max.</td>
<td>30 sec. max.</td>
<td>250 °C</td>
<td>5</td>
<td>max. twice</td>
</tr>
<tr>
<td></td>
<td>63 to 450</td>
<td>40 sec. max.</td>
<td>30 sec. max.</td>
<td>240 °C</td>
<td>5</td>
<td>max. twice</td>
</tr>
<tr>
<td>12.5 up to 18</td>
<td>4 to 50</td>
<td>30 sec. max.</td>
<td>20 sec. max.</td>
<td>245 °C</td>
<td>5</td>
<td>max. twice</td>
</tr>
<tr>
<td></td>
<td>63 to 450</td>
<td>20 sec. max.</td>
<td>5 sec. max.</td>
<td>235 °C</td>
<td>5</td>
<td>max. twice</td>
</tr>
</tbody>
</table>
### 2.2. REFLOW SOLDERING • SMD – SOLID CONDUCTIVE POLYMER CAPACITORS

**Recommended reflow soldering conditions**

#### Classification of reflow soldering profile

<table>
<thead>
<tr>
<th>Profile Features</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Preheat temperature min.</td>
<td>$T_{S \text{ min}}$</td>
</tr>
<tr>
<td>Preheat temperature max.</td>
<td>$T_{S \text{ max}}$</td>
</tr>
<tr>
<td>Preheat time $t_s$ from $T_{S \text{ min}}$ to $T_{S \text{ max}}$</td>
<td>$t_s$</td>
</tr>
<tr>
<td>Ramp-up rate ($T_{L}$ to $T_{p}$)</td>
<td></td>
</tr>
<tr>
<td>Liquidous temperature</td>
<td>$T_{L}$</td>
</tr>
<tr>
<td>Time $t_L$ maintained above $T_{L}$</td>
<td>$t_L$</td>
</tr>
<tr>
<td>Peak package body temperature</td>
<td>$T_{p}$</td>
</tr>
<tr>
<td>Timeframe of within 5°C below ($T_C$) and up to max actual peak body temperature ($T_{p}$)</td>
<td>$t_p$</td>
</tr>
<tr>
<td>Ramp-down rate ($T_{L}$ to $T_{p}$)</td>
<td></td>
</tr>
<tr>
<td>Time 25°C to peak temperature</td>
<td></td>
</tr>
</tbody>
</table>

* Limitations of ramp rates to JEDEC J-STD020E

#### Package classification reflow temperature for SMD – Solid Conductive Polymer Capacitors

<table>
<thead>
<tr>
<th>$V_R$ • Rated Voltage (V)</th>
<th>Time above 200°C</th>
<th>Time above 230°C</th>
<th>$T_{p}$ Peak Temperature</th>
<th>Allowed Reflow Runs</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>90 sec. max.</td>
<td>60 sec. max.</td>
<td>260 °C</td>
<td>only once</td>
</tr>
<tr>
<td>2.5 up to 10</td>
<td></td>
<td></td>
<td>250 °C</td>
<td>max. twice</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>90 sec. max.</td>
<td>60 sec. max.</td>
<td>250 °C</td>
<td>only once</td>
</tr>
<tr>
<td>16 up to 25</td>
<td></td>
<td></td>
<td></td>
<td>max. twice</td>
</tr>
<tr>
<td></td>
<td>80 sec. max.</td>
<td>50 sec. max.</td>
<td>240 °C</td>
<td></td>
</tr>
<tr>
<td>35 up to 100</td>
<td>70 sec. max.</td>
<td>30 sec. max.</td>
<td>240 °C</td>
<td>only once</td>
</tr>
</tbody>
</table>
2.3. REFLOW SOLDERING • SMD MLPC – SOLID POLYMER CONDUCTIVE CAPACITORS

Recommended reflow soldering conditions

![Temperature vs Time Graph](image)

Classification of reflow soldering profile

<table>
<thead>
<tr>
<th>Profile Features</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Preheat temperature min.</td>
<td>( T_{s\ min} ) 150 °C</td>
</tr>
<tr>
<td>Preheat temperature max.</td>
<td>( T_{s\ max} ) 200 °C</td>
</tr>
<tr>
<td>Preheat time ( t_s ) from ( T_{s\ min} ) to ( T_{s\ max} )</td>
<td>( t_s ) 120 seconds</td>
</tr>
<tr>
<td>Ramp-up rate ( (T_s \ to \ T_p) )</td>
<td>max. 3°C/second</td>
</tr>
<tr>
<td>Liquidous temperature</td>
<td>( T_L ) 217 °C</td>
</tr>
<tr>
<td>Time ( t_L ) maintained above ( T_L )</td>
<td>( t_L ) 60 ~ 150 seconds</td>
</tr>
<tr>
<td>Peak package body temperature</td>
<td>( T_P )</td>
</tr>
<tr>
<td>Liquidous temperature</td>
<td>( T_P ) See reference table below for proper Rated Voltage ( V_R )</td>
</tr>
<tr>
<td>Timeframe of within 5°C below and up to max actual peak body temperature</td>
<td>( t_P ) max. 30 seconds</td>
</tr>
<tr>
<td>Ramp-down rate ( (T_L \ to \ T_P) )</td>
<td>max. 6°C/second</td>
</tr>
<tr>
<td>Time 25°C to peak temperature</td>
<td>max. 8 minutes</td>
</tr>
</tbody>
</table>

* Limitations of ramp rates to JEDEC-J-STD020E

Package classification reflow temperature for SMD MLPC – Solid Conductive Polymer Capacitors

<table>
<thead>
<tr>
<th>( V_R ) • Rated Voltage (V)</th>
<th>Time above 200°C</th>
<th>Time above 230°C</th>
<th>( T_P ) • Peak Temperature</th>
<th>Allowed Reflow Runs</th>
</tr>
</thead>
<tbody>
<tr>
<td>2.5 up to 25</td>
<td>90 sec. max.</td>
<td>40 sec. max.</td>
<td>260°C max. 10sec.</td>
<td>max. twice</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>250°C max. 10sec.</td>
<td>max. three times</td>
</tr>
</tbody>
</table>

For further information please contact sales@capxon.org
2.4. REFLOW SOLDERING • SMD – HYBRID CONDUCTIVE POLYMER CAPACITORS

Recommended reflow soldering conditions

Classification of reflow soldering profile

<table>
<thead>
<tr>
<th>Profile Features</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Preheat temperature min.</td>
<td>$T_{s \text{ min}}$ 160 °C</td>
</tr>
<tr>
<td>Preheat temperature max.</td>
<td>$T_{s \text{ max}}$ 200 °C</td>
</tr>
<tr>
<td>Preheat time $t_s$ from $T_{s \text{ min}}$ to $T_{s \text{ max}}$</td>
<td>$t_s$ 120 seconds</td>
</tr>
<tr>
<td>Ramp-up rate ($T_L$ to $T_p$)</td>
<td>max. 3 °C/second</td>
</tr>
<tr>
<td>Liquidous temperature $T_L$</td>
<td>217 °C</td>
</tr>
<tr>
<td>Time $t_L$ maintained above $T_L$</td>
<td>$t_L$ See reference table below for proper Ø Diameter</td>
</tr>
<tr>
<td>Peak package body temperature $T_p$</td>
<td>$T_p$ See reference table below for proper Ø Diameter</td>
</tr>
<tr>
<td>Timeframe of within 5°C below and up to max actual peak body temperature $t_p$</td>
<td>$t_p$ See reference table below for proper Ø Diameter</td>
</tr>
<tr>
<td>Ramp-down rate ($T_L$ to $T_p$)</td>
<td>max. 6 °C/second</td>
</tr>
<tr>
<td>Time 25°C to peak temperature</td>
<td>max. 8 minutes</td>
</tr>
</tbody>
</table>

* Limitations of ramp rates to JEDEC-J-STD020E

Package classification reflow temperature for SMD – Hybrid Conductive Polymer Capacitors

<table>
<thead>
<tr>
<th>Ø Diameter (mm)</th>
<th>Time above 200°C</th>
<th>$t_{L}$ Time above 217°C</th>
<th>Time above 230°C</th>
<th>$T_p$ Peak Temperature (°C)</th>
<th>$t_p$ Timing (seconds)</th>
<th>Allowed Reflow Runs</th>
</tr>
</thead>
<tbody>
<tr>
<td>≤ 6.3</td>
<td>≤ 70 sec. max</td>
<td>≤ 40 sec. max.</td>
<td>≤ 30 sec. max.</td>
<td>260</td>
<td>5</td>
<td>max. twice</td>
</tr>
<tr>
<td>≥ 8</td>
<td>≤ 70 sec. max</td>
<td>≤ 40 sec. max.</td>
<td>≤ 30 sec. max.</td>
<td>245</td>
<td>10</td>
<td>max. twice</td>
</tr>
<tr>
<td></td>
<td>70 sec. max</td>
<td>40 sec. max.</td>
<td>30 sec. max.</td>
<td>260</td>
<td>5</td>
<td>only once</td>
</tr>
</tbody>
</table>
2.5. WAVE SOLDERING • ALL RADIAL & SNAP-IN CAPACITORS

Recommended wave soldering conditions

Classification wave soldering profile • Refer to EN 61760-1: 2006

<table>
<thead>
<tr>
<th>Profile Features</th>
<th>Value • Pb-free Assembly</th>
<th>Value • Sn-Pb Assembly</th>
</tr>
</thead>
<tbody>
<tr>
<td>Preheat temperature min.</td>
<td>$T_{s \text{ min}}$</td>
<td>100 °C</td>
</tr>
<tr>
<td>Preheat temperature typical</td>
<td>$T_{s \text{ typ}}$</td>
<td>120 °C</td>
</tr>
<tr>
<td>Preheat temperature max.</td>
<td>$T_{s \text{ max}}$</td>
<td>130 °C</td>
</tr>
<tr>
<td>Preheat time $t_s$ from $T_{s \text{ min}}$ to $T_{s \text{ max}}$</td>
<td>$t_s$</td>
<td>70 seconds</td>
</tr>
<tr>
<td>Peak temperature</td>
<td>$T_p$</td>
<td>245 °C ~ 260 °C</td>
</tr>
<tr>
<td>Time of actual peak temperature</td>
<td>$t_p$</td>
<td>Max. 10 seconds</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Max. 5 second each wave</td>
</tr>
<tr>
<td>Ramp-down date min.</td>
<td></td>
<td>~ 2 °C/second</td>
</tr>
<tr>
<td>Ramp-down rate typical</td>
<td></td>
<td>~ 3.5 °C/second</td>
</tr>
<tr>
<td>Ramp-down rate max.</td>
<td></td>
<td>~ 5 °C/second</td>
</tr>
<tr>
<td>Time 25°C to 25°C</td>
<td></td>
<td>4 minutes</td>
</tr>
</tbody>
</table>
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